











SNVS822A - DECEMBER 2012 - REVISED NOVEMBER 2014

LM10011

# LM10011 6/4-Bit VID Programmable Current DAC for Point of Load Regulators with **Adjustable Start-Up Current**

#### **Features**

- 1.0% Output Current Accuracy (0°C to 100°C)
- 1.25% Output Current Accuracy (-40°C to 125°C)
- Input Voltage Range: 2.97 V to 5.5 V
- Pin Selectable VID Format (6- or 4-bit)
- 16 Selectable Start-Up Currents
- Precision Enable to Support Custom UVLO
- SON-10 3-mm × 3-mm Footprint, 0.5-mm Pitch
- Footprint Compatible with the LM10010

### **Applications**

- Broadband, Networking, and Wireless Communications
- Notebook Power Solutions
- Portable Instruments
- **Battery-Powered Equipment**
- Powering Digital Loads with a 6-bit or 4-bit, 4-Pin VID Interface

### 3 Description

The LM10011 is a precision, digitally programmable device used to control the output voltage of a DC/DC converter. The LM10011 outputs a dc current proportional to a 6-bit or 4-bit input word. By connecting the IDAC\_OUT pin to the feedback node of a regulator, the regulator output voltage can be adjusted to a desired range and resolution set by the user. As the input word counts up, the output voltage is adjusted higher based on the values of the feedback resistors in the converter.

The current from the IDAC\_OUT pin on start-up is programmable by an external resistor to cover the range of 0 to 56.4 µA with 4 bits of resolution. The MODE pin allows programming of the device through a 4-bit parallel VID interface or through a 6-bit interface consisting of upper and lower 3-bit VID codes. The LM10011 is specifically designed to program a wide variety of Texas Instruments DC/DC VÍD (Voltage Identification) converters applications.

#### Device Information<sup>(1)</sup>

| PART NUMBER | PACKAGE   | BODY SIZE (NOM)   |
|-------------|-----------|-------------------|
| LM10011     | WSON (10) | 3.00 mm × 3.00 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Typical Application Circuit $_{\mathsf{T}}\mathsf{V}_{\mathsf{OUT}}$ VINO VIN SW 2.97V to 5.5V DC/DC **\$**R<sub>FB¹</sub> FΒ **GND** \$R<sub>FB2</sub> 0 - 59.2 uA VDD $V_{\mathsf{CORE}}$ IDAC OUT LM10011 VIDS 9 VIDC VID 8 SET VIDB Interface VIDA **GND** SON-10 3 mm x 3 mm



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## 4 Revision History

### Changes from Original (December 2012) to Revision A

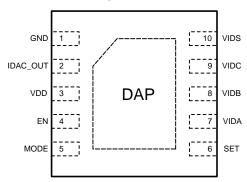
**Page** 

Added Pin Configuration and Functions section, Handling Rating table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information 



## 5 Pin Configuration and Functions





### **Pin Functions**

| PIN NAME NUMBER |     |     |   |  |
|-----------------|-----|-----|---|--|
|                 |     | I/O | DESCRIPTION   |  |
| GND             | 1   | -   | Ground  |  |
| IDAC_OUT        | 2   | 0   | Output pin of the current DAC that connects to the feedback node of the regulator.  |  |
| VDD             | 3   | I   | Positive supply input. Operating voltage is 2.97 V to 5.5 V. It is recommended to add a small 1-nF or greater bypass capacitor from this pin to GND.  |  |
| EN              | 4   | 1   | Precision enable input. The LM10011 will operate when the EN pin voltage exceeds 1.34 V.  |  |
| MODE            | 5   | _   | MODE will set the VID operating mode. Connecting MODE to VDD will select a 4-bit parallel interface. Connecting MODE to GND will select a 4-pin, 6-bit interface.                                 |  |
| SET             | 6   | _   | A resistor connected from SET to GND will set the start-up code (current) at the IDAC_OUT pin. There are 16 different start-up codes to select from.  |  |
| VIDA            | 7   | I   | VID digital input. In 6-bit mode: Bit 0 when VIDS transitions low; Bit 3 when VIDS transitions high. In 4-bit mode: Bit 0.  |  |
| VIDB            | 8   | I   | VID digital input. In 6-bit mode: Bit 1 when VIDS transitions low; Bit 4 when VIDS transitions high. In 4-bit mode: Bit 1.  |  |
| VIDC            | 9   | I   | VID digital input. In 6-bit mode: Bit 2 when VIDS transitions low; Bit 5 when VIDS transitions high. In 4-bit mode: Bit 2.  |  |
| VIDS            | 10  | I   | VID select line. In 6-bit mode: transition low selects lower 3 bits, transition high selects upper 3 bits and updates the IDAC_OUT current to reflect the present VID code. In 4-bit mode: Bit 3. |  |
| DAP             | DAP | _   | Die Attach Pad. Not electrically connected to device, connect to system ground plane for reduced thermal resistance.  |  |

## 6 Specifications

## 6.1 Absolute Maximum Ratings (1)(2)

over operating free-air temperature range (unless otherwise noted)

|                         | MIN  | MAX | UNIT |
|-------------------------|------|-----|------|
| VDD, EN, IDAC_OUT, MODE | -0.3 | 6   | V    |
| VIDA, VIDB, VIDC, VIDS  | -0.3 | 6   | V    |
| Junction Temperature    |      | 150 | °C   |

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur.

<sup>(2)</sup> If Military- or Aerospace-specified devices are required, please contact the Texas Instruments Sales Office / Distributors for availability and specifications.



### 6.2 Handling Ratings

|                    |                         |  | MIN | MAX | UNIT |
|--------------------|-------------------------|--|-----|-----|------|
| T <sub>stg</sub>   | Storage temperature ran | ge   | -65 | 150 | °C   |
| V <sub>(ESD)</sub> | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins (1)                         |     | 2   | 1.37 |
|                    |                         | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup> |     | 1   | kV   |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

|                                  | MIN  | MAX        | UNIT |
|----------------------------------|------|------------|------|
| VDD                              | 2.97 | 5.5        | V    |
| IDAC_OUT                         | -0.3 | VDD – 1.75 | V    |
| VIDA, VIDB, VIDC, VIDS, EN, MODE | -0.3 | 5.5        | V    |
| Junction Temperature             | -40  | 125        | °C   |
| Ambient Temperature              | -40  | 125        | °C   |

#### 6.4 Thermal Information

|                       |   | LM10011 |       |
|-----------------------|---|---------|-------|
|                       | THERMAL METRIC <sup>(1)</sup>                               | DSC     | UNIT  |
|                       |   | 10 PINS |       |
| $R_{\theta JA}$       | Junction-to-ambient thermal resistance (2)                  | 52.1    |       |
| $R_{\theta JC(top)}$  | Junction-to-case (top) thermal resistance (3)               | 30.6    |       |
| $R_{\theta JB}$       | Junction-to-board thermal resistance (4)                    | 26.8    | °C/W  |
| ΨЈТ                   | Junction-to-top characterization parameter <sup>(5)</sup>   | 0.9     | *C/vv |
| ΨЈВ                   | Junction-to-board characterization parameter (6)            | 26.9    |       |
| R <sub>0JC(bot)</sub> | Junction-to-case (bottom) thermal resistance <sup>(7)</sup> | 7.7     |       |

- (1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, SPRA953.
- (2) The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a JEDEC-standard, high-K board, as specified in JESD51-7, in an environment described in JESD51-2a.
- (3) The junction-to-case (top) thermal resistance is obtained by simulating a cold plate test on the package top. No specific JEDEC-standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.
- (4) The junction-to-board thermal resistance is obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.
- (5) The junction-to-top characterization parameter, ψ<sub>JT</sub>, estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining R<sub>θJA</sub>, using a procedure described in JESD51-2a (sections 6 and 7).
- (6) The junction-to-board characterization parameter, ψ<sub>JB</sub>, estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining R<sub>θJA</sub>, using a procedure described in JESD51-2a (sections 6 and 7).
- (7) The junction-to-case (bottom) thermal resistance is obtained by simulating a cold plate test on the exposed (power) pad. No specific JEDEC standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.



### 6.5 Electrical Characteristics

Typical values correspond to T<sub>J</sub> = 25°C. Minimum and maximum limits apply over -40°C to 125°C junction temperature range unless otherwise stated. (1)(2)

|               | PARAMETER                                  | TEST CONDITIONS   | MIN   | TYP  | MAX  | UNIT  |
|---------------|--|---|-------|------|------|-------|
| SUPPLY, UVLO, | AND ENABLE                                 |   |       |      |      |       |
| IQ            | Quiescent current                          | VDD = 5.0 V, V <sub>EN</sub> = 2.0 V                                    |       | 260  | 300  | μA    |
| IQ_FS         | Quiescent current, IDAC_OUT = IFS_6        | VDD = 5.0 V, V <sub>EN</sub> = 2.0 V, IFS_6                             |       | 382  |      | μA    |
| IQ_DIS        | Quiescent current disabled                 | VDD = 5.0 V, V <sub>EN</sub> = 0.0 V                                    |       | 45   | 65   | μA    |
| VUVLO_R       | Undervoltage rising threshold              | VDD rising  |       | 2.65 | 2.95 | V     |
| VUVLO_F       | Undervoltage falling threshold             | VDD falling   | 2.2   | 2.45 |      | V     |
| VUVLO_HYS     | Hysteresis                                 |   |       | 200  |      | mV    |
| VEN           | Enable rising threshold                    | V <sub>EN</sub> rising  | 1.20  | 1.34 | 1.45 | V     |
| VEN_HYS       | Enable hysteresis                          |   | 50    | 100  | 180  | mV    |
| IEN           | Enable pullup current                      |   |       | 2    |      | μΑ    |
| IDAC_OUT      |  |   |       |      |      |       |
| ACC           | Accuracy                                   | Measured at full scale  | -1.25 |      | 1.25 | %     |
| ACC           | Accuracy                                   | Measured at full scale, 0°C to 100°C                                    | -1.0  |      | 1.0  | %     |
| LSB_6         | DAC step size, 6-bit mode                  | IFS_6 / (2 <sup>6</sup> – 1)  |       | 940  |      | nA    |
| LSB_4         | DAC step size, 4-bit mode                  | IFS_4 / (2 <sup>4</sup> – 1)  |       | 3.76 |      | μA    |
| IFS_6         | Full-scale output current (6-bit mode)     | VID[5:0] = 000000b  |       | 59.2 |      | μA    |
| IFS_4         | Full-scale output current (4-bit mode)     | VID[3:0] = 0000b  |       | 56.4 |      | μA    |
| INL           | Integral non-linearity                     |   | -1    |      | 1    | LSB_6 |
| DNL           | Differential non-linearity                 |   | -0.25 |      | 0.25 | LSB_6 |
| OFFSET        | Offset current                             | VID[5:0] = 111111b (6-bit), VID[3:0] = 1111b (4-bit)                    |       | 60   |      | nA    |
| VOUT_MAX      | IDAC_OUT compliance voltage                | VDD = 3 V, VDD-V <sub>IDAC OUT</sub>                                    |       |      | 1.75 | V     |
| START-UP SET  | CURRENT                                    | 1-11  |       |      |      |       |
| VSETFSR       | SET pin voltage FSR                        |   | 1.12  | 1.2  | 1.23 | V     |
| SETRES        | SET ADC resolution                         |   |       | 4    |      | bits  |
| SETRNG        | SET ADC current full-scale range           |   |       | 56.4 |      | μA    |
| ISET          | SET Current                                |   | 4.75  | 5.1  | 5.40 | μA    |
| SET0          | Start-up DAC error, code 0                 | $R_{SET} = 0 \Omega$ , $I_{DAC\_OUT} = 56.4 \mu A$                      | 0     |      | 0    | LSB   |
| SET1          | Start-up DAC error, code 1                 | $R_{SET} = 21.0 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 52.7 \mu\text{A}$ | 0     |      | 0    | LSB   |
| SET2          | Start-up DAC error, code 2                 | $R_{SET} = 35.7 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 48.9 \mu\text{A}$ | 0     |      | 0    | LSB   |
| SET3          | Start-up DAC error, code 3                 | $R_{SET} = 51.1 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 45.2 \mu\text{A}$ | 0     |      | 0    | LSB   |
| SET4          | Start-up DAC error, code 4 <sup>(4)</sup>  | $R_{SET} = 71.5 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 41.4 \mu\text{A}$ | 0     |      | 1    | LSB   |
| SET5          | Start-up DAC error, code 5 <sup>(4)</sup>  | $R_{SET} = 86.6 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 37.7 \mu\text{A}$ | 0     |      | 1    | LSB   |
| SET6          | Start-up DAC error, code 6 <sup>(4)</sup>  | $R_{SET} = 105 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 33.9 \mu\text{A}$  | 0     |      | 1    | LSB   |
| SET7          | Start-up DAC error, code 7 <sup>(4)</sup>  | $R_{SET} = 118 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 30.1 \mu\text{A}$  | 0     |      | 1    | LSB   |
| SET8          | Start-up DAC error, code 8 <sup>(4)</sup>  | $R_{SET} = 140 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 26.4 \mu\text{A}$  | 0     |      | 1    | LSB   |
| SET9          | Start-up DAC error, code 9 <sup>(4)</sup>  | $R_{SET} = 154 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 22.6 \mu\text{A}$  | 0     |      | 1    | LSB   |
| SET10         | Start-up DAC error, code 10 <sup>(4)</sup> | $R_{SET} = 169 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 18.8  \mu\text{A}$ | 0     |      | 1    | LSB   |
| SET11         | Start-up DAC error, code 11 <sup>(4)</sup> | $R_{SET} = 182 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 15.1 \mu\text{A}$  | 0     |      | 1    | LSB   |
| SET12         | Start-up DAC error, code 12 <sup>(4)</sup> | $R_{SET}$ = 200 k $\Omega^{(3)}$ , $I_{DAC\_OUT}$ = 11.3 $\mu A$        | 0     |      | 1    | LSB   |
| SET13         | Start-up DAC error, code 13 <sup>(4)</sup> | $R_{SET} = 215 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 7.59 \mu\text{A}$  | 0     |      | 1    | LSB   |
| SET14         | Start-up DAC error, code 14 <sup>(4)</sup> | $R_{SET} = 237 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 3.80 \mu\text{A}$  | 0     |      | 1    | LSB   |
| SET15         | Start-up DAC error, code 15                | $R_{SET} = 301 \text{ k}\Omega^{(3)}, I_{DAC\_OUT} = 0.06 \mu\text{A}$  | 0     | -    | 0    | LSB   |

<sup>(1)</sup> All hot and cold limits are specified by correlating the electrical characteristics to process and temperature variations and applying statistical process control.

The junction temperature (T<sub>J</sub> in °C) is calculated from the ambient temperature (T<sub>A</sub> in °C) and power dissipation (P<sub>D</sub> in Watts) as follows:  $T_J = T_A + (P_D \times R_{\theta JA})$  where  $R_{\theta JA}$  (in °C/W) is the package thermal impedance provided in the *Thermal Information* section.  $R_{SET}$  is based on 1% E96 standard resistor values.

<sup>(4) &</sup>quot;+1" LSB implies a positive step in CODE. LSB is in reference to LSB\_4.



### **Electrical Characteristics (continued)**

Typical values correspond to  $T_J$  = 25°C. Minimum and maximum limits apply over -40°C to 125°C junction temperature range unless otherwise stated. (1)(2)

|                       | PARAMETER                                 | TEST CONDITIONS                    | MIN      | TYP | MAX  | UNIT |
|-----------------------|---|------------------------------------|----------|-----|------|------|
| VID LOGIC INP         | UTS <sup>(5)</sup>                        |                                    | <u>'</u> |     | ·    |      |
| V <sub>IL</sub>       | Input voltage low                         |                                    |          |     | 0.75 | V    |
| V <sub>IH</sub>       | Input voltage high                        |                                    | 1.0      |     |      | V    |
| I <sub>IL</sub>       | Input current low                         |                                    | -3.5     |     |      | μA   |
| I <sub>IH</sub>       | Input current high                        |                                    |          |     | 5    | μΑ   |
| t <sub>DEGLITCH</sub> | Input deglitch time                       |                                    |          | 3.6 |      | μs   |
| t <sub>1</sub>        | Input delay time                          | VIDS rising edge                   |          |     | 1    | μs   |
| t <sub>2</sub>        | Input hold time VIDA, VIDB, VIDC valid    | VIDS falling edge                  | 20       |     |      | μs   |
| t <sub>3</sub>        | Input delay time                          | VIDS falling edge                  |          |     | 1    | μs   |
| t <sub>4</sub>        | Input hold time VIDA, VIDB, VIDC valid    | VIDS rising edge                   | 20       |     |      | μs   |
| t <sub>5</sub>        | Delay to beginning of IDAC_OUT transition | Measured from VIDS rising edge     |          | 6.3 | 10   | μs   |
| t <sub>6</sub>        | IDAC_OUT transition time                  | Time constant for exponential rise |          | 40  |      | μs   |
| t <sub>7</sub>        | Minimum hold time in 4-bit mode           | VIDA, VIDB, VIDC, VIDS             |          | 4.4 |      | μs   |

(5) For VID timing, see Figure 1.

### **6 BIT MODE TIMING**

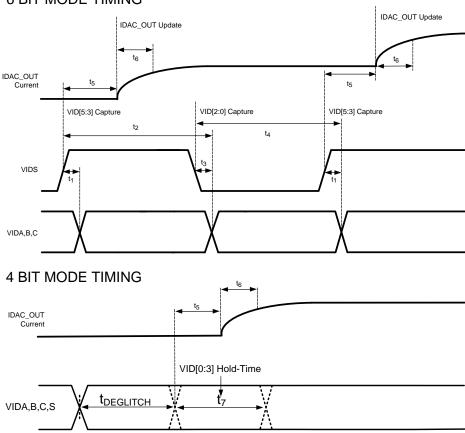
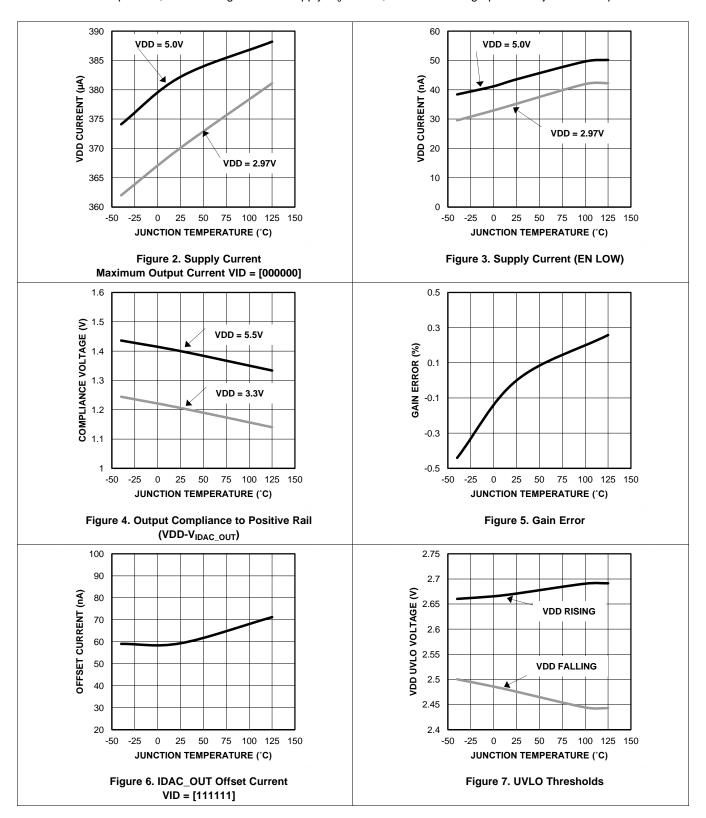


Figure 1. Timing Diagram for LM10011 Communications



## 6.6 Typical Characteristics

Unless otherwise specified, the following conditions apply: T<sub>J</sub> = 25°C, VDD = 5 V. All graphs show junction temperature.

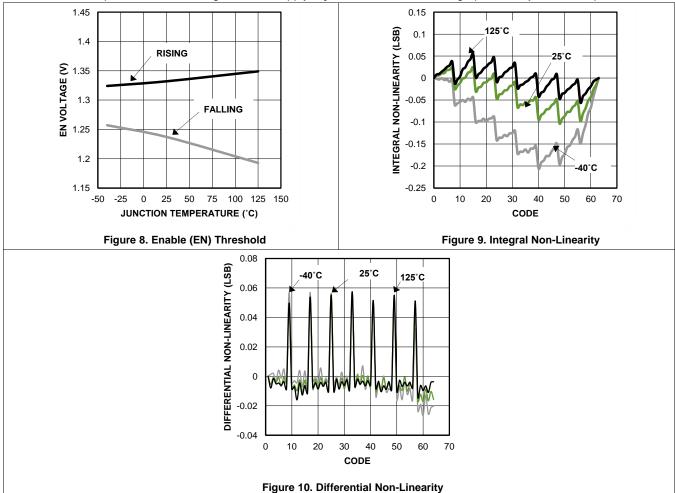


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## **Typical Characteristics (continued)**

Unless otherwise specified, the following conditions apply:  $T_J = 25$ °C, VDD = 5 V. All graphs show junction temperature.





### 7 Detailed Description

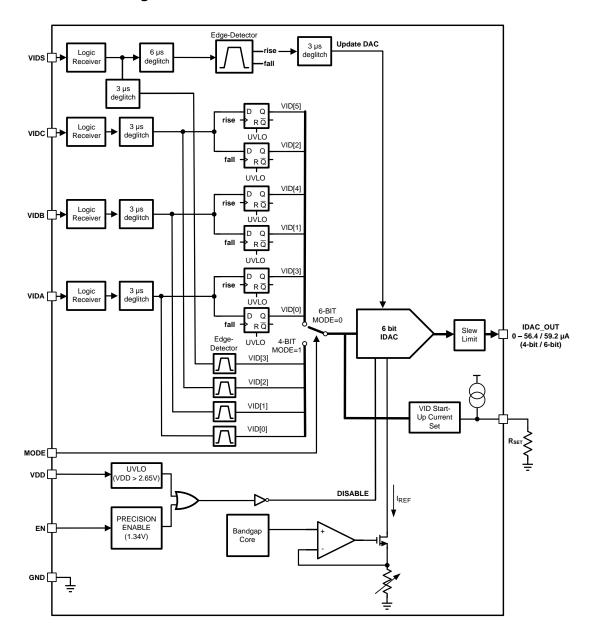
#### 7.1 Overview

The LM10011 is a precision current DAC used for controlling any point of load regulator with an adjustable resistor feedback network. Four VID communication lines (VIDA, VIDB, VIDC, and VIDS) are used to write a 6-bit or 4-bit VID value. The output of the IDAC (IDAC\_OUT) is used to inject a precision current into the feedback node of a regulator, thus adjusting the output voltage. With this method, it is possible to precisely control the output voltage of the regulator.

An enable pin (EN) is provided to allow for a reduced quiescent current when not in use. Also, the VDD line is monitored so that an undervoltage event will shutdown the LM10011 (IDAC\_OUT =  $0.0 \mu A$ ).

The device is available in a 10-pad No-Pullback Package (SON-10). The LM10011 can be used in numerous applications with regulators from 2.97-V to 5.5-V supplies.

### 7.2 Functional Block Diagram





#### 7.3 Feature Description

The LM10011 can be treated as a D/A converter, converting digital VID codes to analog outputs. The LM10011 DAC analog output is a current that flows out of the IDAC\_OUT pin. The IDAC\_OUT pin is intended to be connected to the feedback node of a voltage regulator as shown in Figure 11. In a typical voltage regulator, the current in  $R_{FB2}$  is constant by virtue of the regulator feedback loop maintaining the reference voltage at the feedback node. The current flowing through  $R_{FB2}$  is the same current flowing through  $R_{FB1}$ . When current is injected into the feedback node by the LM10011, less current is required from the  $R_{FB1}$  resistor. The consequence of this is that the output voltage of the regulator will decrease to maintain the total amount of current in  $R_{FB2}$  to regulate at the correct feedback (reference) voltage.

Each VID code corresponds to a different IDAC\_OUT current and thus a different output voltage. Increasing the VID code lowers the IDAC\_OUT current and raises the output voltage. Decreasing the VID code raises the IDAC\_OUT current and lowers the output voltage. All VID codes are decoded into a 6-bit or 4-bit current DAC output whether the MODE equals 0 (connected to GND) or 1 (connected to VDD), respectively.

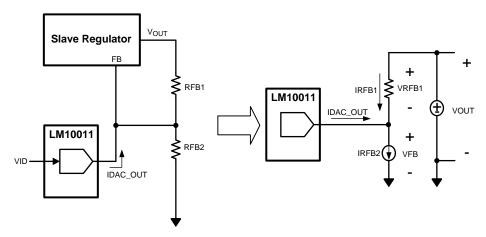


Figure 11. Output Voltage (Vout) is Controlled Via Current Injection into the Feedback Node

#### 7.3.1 Current DAC

The LM10011 current DAC is based on a low-voltage bandgap reference setting a current through a precision adjustable resistor. This bandgap is trimmed for precision and gives excellent performance over temperature. The output current has a maximum full-scale range [VID = 000000b] of 59.2  $\mu$ A and is adjustable with a 6- or 4-bit VID word. This allows for 64 or 16 settings with a resolution of 940 nA or 3.76  $\mu$ A, respectively. The current DAC also has a slew limit to prevent abrupt changes in the output. The slew limit is represented as a time constant,  $t_6$  = 40  $\mu$ s, in the *Electrical Characteristics* table. A deglitch filter for the VID inputs provides noise immunity and effectively adds a small delay from the transition of a VID line to the change in IDAC OUT current.

#### 7.3.2 Enable Pin and UVLO

The enable (EN) pin allows the output of the device to be enabled or disabled (IDAC\_OUT =  $0.0~\mu$ A) with an external control signal. This pin is a precision analog input that enables the device when the voltage exceeds 1.34~V. The EN pin has 100~mV of hysteresis and will disable the output when the enable voltage falls below 1.23~V. If EN is not used, it can be left open, and will be pulled high by an internal  $2-\mu$ A current source. Since the EN pin has a precise turn-on threshold it can be used along with an external resistor divider network from VDD to configure the device to turn on at a precise input voltage.

The LM10011 has a built-in undervoltage lockout (UVLO) protection circuit that keeps the device from operating until the input voltage reaches 2.65 V (typical). The UVLO threshold has 200 mV of hysteresis that keeps the LM10011 from responding to power-on glitches during start-up. Note that descending below the EN voltage and/or the UVLO voltage are functionally the same as a reset. Bringing the device back from a low enable setting or from a VDD UVLO event will reset the IDAC\_OUT current to its start-up R<sub>SET</sub> setting.



#### 7.4 Device Functional Modes

Table 1 lists the functional modes of the LM10011 device.

Table 1. Mode Pin Summary

| MODE PIN CONNECTION | LOGIC STATE | DESCRIPTION |
|---------------------|-------------|-------------|
| GND                 | 0           | 6-bit mode  |
| VDD                 | 1           | 4-bit mode  |

### 7.5 Programming

### 7.5.1 VID Programming, 6-Bit Mode

Four pins are used to communicate with the LM10011. In 6-bit mode (MODE = 0), VIDA, VIDB, and VIDC are data lines, while VIDS is a latching strobe that programs in the LM10011 data. As shown in the 6-bit mode timing diagram of Figure 1, the falling edge of VIDS latches in the data from VIDA, VIDB, and VIDC as the lower three LSB of the IDAC\_OUT value, [2:0]. After a minimum hold time ( $t_2$ ), the rising edge of VIDS latches in the data from VIDA, VIDB, and VIDC as the upper three LSB of the IDAC\_OUT value, [5:3]. Internally, a delay ( $t_3$ , $t_1$ ) on VIDS allows for the setting of all VIDA, VIDB, and VIDC lines to change simultaneously as VIDS rises or falls.

### 7.5.2 VID Programming, 4-Bit Mode

The LM10011 includes a 4-bit mode to facilitate parallel VID communication. In 4-bit mode (MODE = 1), VIDC, VIDB, VIDA, and VIDS are all parallel data lines. As shown in the 4-bit mode timing diagram in Figure 1, a changing edge of any of the VID communication lines will change the IDAC\_OUT current to the corresponding new 4-bit value found on the data lines. There is a 3- $\mu$ s deglitch filter to eliminate spurious noise events. The data must overcome the deglitch time and the minimum hold time ( $t_7$ ) or else the IDAC\_OUT pin current may not reflect the value indicated at the VID data inputs. During the hold time, no other data line can be transitioned.

As mentioned in a previous section, for both the 4-bit and 6-bit mode, the VID data word is set so that the lowest output current is seen at the highest VID data word (59.2  $\mu$ A at a code of 0d in 6-bit mode and 56.4  $\mu$ A in 4-bit mode). Conversely, the lowest current is seen at the highest VID data word (0.06  $\mu$ A at 63d or 15d). During VID operation with the regulator, this will translate to the lowest output voltage with the lowest VID word, 0d, and the highest output voltage with the highest VID word, 63d or 15d. The communications pins can be used with a low-voltage microcontroller with a maximum V<sub>II</sub> of 0.75 V and a minimum V<sub>IH</sub> of 1.0 V.

#### 7.5.3 Programming the Start-Up Current

Depending on the value of  $R_{SET}$  during start-up (when VDD > VUVLO\_R and EN > VEN), the output current on the IDAC\_OUT pin will take on 1 of 16 discrete values corresponding to the currents available in the 4-bit mode. These discrete start-up currents can be programmed by connecting a resistor ( $R_{SET}$ ) from the SET pin to GND. If the EN voltage is toggled or a UVLO is triggered during operation, the current will default back to the value set by the  $R_{SET}$  resistor. It takes only one VID command transition in either 4-bit or 6-bit mode to change the current to something other than the pre-programmed start-up current. The required  $R_{SET}$  resistors and their corresponding start-up currents codes can be found in Table 2.

Table 2. Start-Up-4-Bit Mode Currents with Corresponding R<sub>SET</sub> Values and Output Currents

| VID CODE   | NOMINAL IDAC_OUT CURRENT (μA) | R <sub>SET</sub> (kΩ) |
|------------|-------------------------------|-----------------------|
| 0000b (0d) | 56.4                          | 0                     |
| 0001b (1d) | 52.7                          | 21.0                  |
| 0010b (2d) | 48.9                          | 35.7                  |
| 0011b (3d) | 45.2                          | 51.1                  |
| 0100b (4d) | 41.4                          | 71.5                  |
| 0101b (5d) | 37.7                          | 86.6                  |
| 0110b (6d) | 33.9                          | 105                   |
| 0111b (7d) | 30.1                          | 118                   |
| 1000b (8d) | 26.4                          | 140                   |
| 1001b (9d) | 22.6                          | 154                   |



### **Programming (continued)**

Table 2. Start-Up-4-Bit Mode Currents with Corresponding R<sub>SET</sub> Values and Output Currents (continued)

| VID CODE    | NOMINAL IDAC_OUT CURRENT (μA) | R <sub>SET</sub> (kΩ) |
|-------------|-------------------------------|-----------------------|
| 1010b (10d) | 18.8                          | 169                   |
| 1011b (11d) | 15.1                          | 182                   |
| 1100b (12d) | 11.3                          | 200                   |
| 1101b (13d) | 7.59                          | 215                   |
| 1110b (14d) | 3.80                          | 237                   |
| 1111b (15d) | 0.06                          | 301                   |

Codes 0100b (4d) through 1110b (14d) will start-up into either the selected code or 1 code higher. This means that the output voltage of the POL may start-up into the selected output voltage or 1 LSB higher.

### 7.5.4 IDAC\_OUT Current Values

Table 3. IDAC\_OUT Currents and Corresponding VID Codes

| VID CODE (6-BIT [4-BIT]) | IDAC CURRENT (μA) |
|--------------------------|-------------------|
| 0d                       | 59.2              |
| 1d                       | 58.3              |
|                          | 57.4              |
| 2d (0d)                  |                   |
| 3d [0d]                  | 56.4              |
| 4d                       | 55.5              |
| 5d                       | 54.6              |
| 6d                       | 53.6              |
| 7d [1d]                  | 52.7              |
| 8d                       | 51.7              |
| 9d                       | 50.8              |
| 10d                      | 49.8              |
| 11d [2d]                 | 48.9              |
| 12d                      | 48.0              |
| 13d                      | 47.0              |
| 14d                      | 46.1              |
| 15d [3d]                 | 45.2              |
| 16d                      | 44.2              |
| 17d                      | 43.3              |
| 18d                      | 42.3              |
| 19d [4d]                 | 41.4              |
| 20d                      | 40.5              |
| 21d                      | 39.5              |
| 22d                      | 38.6              |
| 23d [5d]                 | 37.7              |
| 24d                      | 36.7              |
| 25d                      | 35.7              |
| 26d                      | 34.8              |
| 27d [6d]                 | 33.9              |
| 28d                      | 33.0              |
| 29d                      | 32.0              |
| 30d                      | 31.1              |
| 31d [7d]                 | 30.1              |
| ال ما ما ما              | 00.1              |

Table 3. IDAC\_OUT Currents and Corresponding VID Codes (continued)

| VID CODE (6-BIT [4-BIT]) | IDAC CURRENT (μA) |
|--------------------------|-------------------|
| 32d                      | 29.2              |
| 33d                      | 28.2              |
| 34d                      | 27.3              |
| 35d [8d]                 | 26.4              |
| 36d                      | 25.4              |
| 37d                      | 24.5              |
| 38d                      | 23.6              |
| 39d [9d]                 | 22.6              |
| 40d                      | 21.6              |
| 41d                      | 20.7              |
| 42d                      | 19.8              |
| 43d [10d]                | 18.8              |
| 44d                      | 17.9              |
| 45d                      | 17.0              |
| 46d                      | 16.0              |
| 47d [11d]                | 15.1              |
| 48d                      | 14.1              |
| 49d                      | 13.2              |
| 50d                      | 12.3              |
| 51d [12d]                | 11.3              |
| 52d                      | 10.4              |
| 53d                      | 9.50              |
| 54d                      | 8.52              |
| 55d [13d]                | 7.59              |
| 56d                      | 6.60              |
| 57d                      | 5.70              |
| 58d                      | 4.74              |
| 59d [14d]                | 3.80              |
| 60d                      | 2.87              |
| 61d                      | 1.93              |
| 62d                      | 1.00              |
| 63d [15d]                | 0.06              |

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## 8 Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

LM10011 is a precision, digitally programmable device used for controlling the dc-dc converter output voltage. The LM10011 GUI design tool is available at <a href="https://www.ti.com/product/LM10011">www.ti.com/product/LM10011</a> and can be used to program any voltage regulator output to a desired range and resolution. The GUI enables changing the output voltage of the on-board POL based on direct user input. It is also able to assist the power designer in selecting the correct external components needed for any given application.

### 8.2 Typical Application

In this example, an LM21215A-1 is used as the voltage regulator and the desired range of output voltage operation is 0.7 V to 1.1 V. The LM10011 can provide control of the output voltage within this range with 6 bits or 4 bits of resolution. For this example, the 400 mV of voltage range translates to a  $V_{OUT\_LSB}$  of 400 mV / 63 = 6.4 mV (26.7 mV in 4-bit mode) at the regulator output. In this calculation, 1% resistor values are used. A schematic for this example is shown in Figure 12.

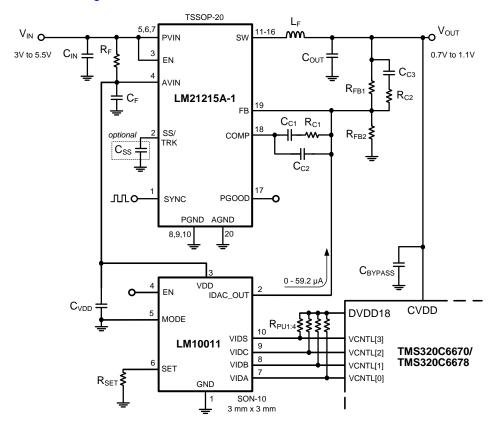


Figure 12. 6-Bit Mode Design Example



### **Typical Application (continued)**

#### 8.2.1 Design Requirements

Table 4 lists the design parameters.

**Table 4. Design Parameters** 

| DESIGN PARAMETER     | EXAMPLE VALUE  |
|----------------------|----------------|
| Output voltage range | 0.7 V to 1.1 V |
| Startup voltage      | 1.1 V          |
| Mode                 | 0              |

#### 8.2.2 Detailed Design Procedure

#### 8.2.2.1 Setting the $V_{OUT}$ Range and LSB

Looking at the Typical Application Circuit in Figure 12, the following equation defines  $V_{OUT}$  of a given regulator (valid for  $V_{OUT} > V_{FB}$ ):

$$V_{OUT} = V_{FB} x \left( 1 + \frac{R_{FB1}}{R_{FB2}} \right) - IDAC\_OUT x R_{FB1}$$
(1)

Here, the output voltage is a function of the resistor divider from  $R_{FB1}$  and  $R_{FB2}$ . Using the LM10011, there is a current supplied by the IDAC\_OUT pin that helps drive current through the feedback resistor  $R_{FB2}$ , thus lowering the necessary current supplied through  $R_{FB1}$ , and hence lowering  $V_{OUT}$ . To calculate the nominal (maximum)  $V_{OUT}$ , use an IDAC\_OUT value of 0  $\mu$ A.

The change in the output voltage can be analyzed based on the resolution of the current DAC from the LM10011 compared to the desired resolution of the output swing of the regulator.  $R_{FB1}$  is designed to provide the desired  $V_{OUT\ LSB}$  with the equation:

$$V_{OUT\_LSB} = LSB \times R_{FB1}$$
 (2)

Where LSB = LSB\_6 (940 nA) from the electrical characteristics table (see *Electrical Characteristics*). Based on the desired nominal  $V_{OUT}$  (with IDAC\_OUT = 0  $\mu$ A) and the calculated  $R_{FB1}$  from Equation 2,  $R_{FB2}$  can be solved using Equation 1.

### 8.2.2.2 4-Bit Mode Design Example

Designing with the LM10011 in 4-bit mode is similar to designing in 6-bit mode. The only differences are the LSB value (LSB = LSB\_4 =  $3.76 \mu A$ ) in Equation 2 and full-scale current range (IDAC\_OUT =  $56.4 \mu A$ ).

### 8.2.2.3 Setting the Start-Up Voltage with R<sub>SET</sub>

 $R_{SET}$  is chosen depending on the required start-up voltage for the particular application. The user must use Equation 3 and solve for the required IDAC\_OUT by inputting the known values of  $R_{FB1}$  and  $R_{FB2}$ ,  $V_{FB}$ , and the desired start-up output voltage,  $V_{OUT}$ . Once IDAC\_OUT is solved for, choose an  $R_{SET}$  based on Table 2 to select a start-up code to yield a current closely matching the calculated result. Use the equation below to solve for the required IDAC\_OUT value at start-up.

$$IDAC\_OUT = \frac{1}{R_{FB1}} \left( V_{FB} \times \left( 1 + \frac{R_{FB1}}{R_{FB2}} \right) - V_{OUT} \right)$$
(3)

#### 8.2.2.4 Example Solution

While in 6-bit mode, assuming a 400-mV output range, 64 VID codes, and an IDAC LSB of 0.940  $\mu$ A, it is desired to have a V<sub>OUT</sub> with an LSB of 6.4 mV and a default value of 1.1 V with a 1.05-V start-up voltage using an LM21215A-1 regulator (V<sub>FB</sub> = 0.6 V):

$$6.4\text{mV} = 0.940\mu\text{A} \times \text{R}_{\text{FB1}}$$
 (4)

$$R_{FB1} = 6.8k\Omega \tag{5}$$

Using 1% standard resistor values,  $R_{FB1}$  can be set to 6.81 k $\Omega$ . Now calculate  $R_{FB2}$  based on  $R_{FB1}$  and the maximum  $V_{OUT}$  of 1.1 V using Equation 1.



1.1V = .6V x 
$$\left(1 + \frac{6.81 \text{k}\Omega}{R_{\text{FB2}}}\right)$$
-0V (6)  
R<sub>FB2</sub> = 8.1k $\Omega$  (7)

Using 1% standard resistor values,  $R_{FB2}$  can be set to 8.06 k $\Omega$ . This will yield a regulator output range of 0.704 V (CODE 0d) to 1.107 V (CODE 63d). Values calculated here will be dependent on the accuracy of the regulator, the LM10011 IDAC OUT, and the resistor values used in the circuit.

Table 5 shows the codes and some of the resultant values of the IDAC current and the corresponding regulator output voltage for the previous example.

Table 5. 6-Bit VID Codes with IDAC Current and Regulator Voltage for the Example in Figure 12.

| VID CODE      | IDAC_OUT CURRENT (μA) | REGULATOR VOLTAGE (V) |
|---------------|-----------------------|-----------------------|
| 000000b (0d)  | 59.2                  | 0.704                 |
| 000001b (1d)  | 58.3                  | 0.710                 |
| 000010b (2d)  | 57.4                  | 0.716                 |
| 000011b (3d)  | 56.4                  | 0.729                 |
|               |                       |                       |
| 111100b (60d) | 2.87                  | 1.087                 |
| 111101b (61d) | 1.93                  | 1.094                 |
| 111110b (62d) | 1.00                  | 1.100                 |
| 111111b (63d) | 0.06                  | 1.107                 |

The required IDAC\_OUT value during start-up can be calculated based on the desired start-up voltage of 1.05 V and the  $R_{FB1}$  and  $R_{FB2}$  resistors found in the previous calculations. Using Equation 3 to solve for the required start-up IDAC\_OUT current results in a start-up current of 8.36  $\mu$ A.

IDAC\_OUT = 
$$\frac{1}{6.81 \text{k}\Omega} \left[ 0.6 \text{V} \times \left[ 1 + \frac{6.81 \text{k}\Omega}{8.06 \text{k}\Omega} \right] - 1.05 \text{V} \right] = 8.36 \mu\text{A}$$
 (8)

Choose a resistor in Table 2 that selects a start-up code that produces a current close to 8.36  $\mu$ A. An R<sub>SET</sub> of 215 k $\Omega$  selects a nominal start-up code of 13d yielding a current of 7.59  $\mu$ A and start-up voltage of 1.054 V.

#### NOTE

Using an  $R_{SET}$  of 215 k $\Omega$  may also select a code of 14d (+1 LSB) yielding a current of 3.80  $\mu A$  and a start-up voltage of 1.081 V.

#### 8.2.3 Application Curves

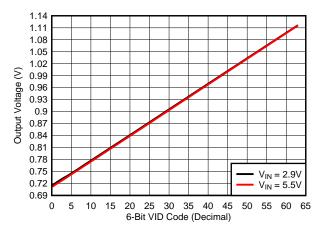


Figure 13. Output Voltage vs. Code for LM21k with LM10011



### 9 Power Supply Recommendations

The LM10011 can be driven from a PWM controller  $V_{DD}$  pin or from the  $V_{IN}$  supply pin as shown in Figure 12. To ensure reliable operation, the LM10011  $V_{DD}$  input power supply must be limited to 6 V maximum.

### 10 Layout

### 10.1 Layout Guidelines

The following guidelines should be followed when designing the PC board for the LM10011:

- Place the LM10011 close to the regulator feedback pin to minimize the FB trace length.
- Place a small capacitor, C<sub>VDD</sub>, (1 nF) directly adjacent to the VDD and GND pins of the LM10011 to help minimize transients which may occur on the input supply line.
- The high-current path from the board input to the load and the return path should be parallel and close to each other to minimize loop inductance.
- The ground connections for the various components around the LM10011 should be connected directly to each other, and to the LM10011 GND pins, and then connected to the system ground at one point. Do not connect the various component grounds to each other through the high-current ground line.
- For additional information about the operation of the regulator, please consult the respective data sheet and application notes on the respective evaluation boards.



### 10.2 Layout Example

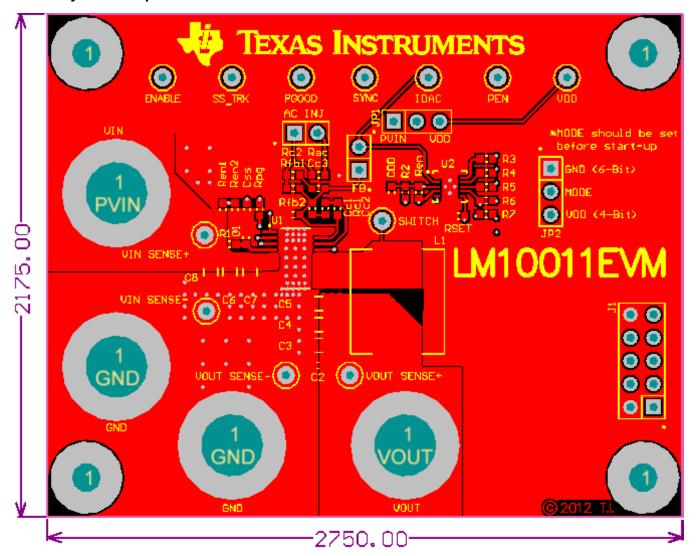


Figure 14. Typical Top Layer Layout



### 11 Device and Documentation Support

#### 11.1 Trademarks

All trademarks are the property of their respective owners.

### 11.2 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 11.3 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

### 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Product Folder Links: *LM10011* 

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### PACKAGE OPTION ADDENDUM

10-Dec-2020

#### **PACKAGING INFORMATION**

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| Orderable Device | Status | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan     | Lead finish/<br>Ball material | MSL Peak Temp      | Op Temp (°C) | Device Marking<br>(4/5) | Samples |
|------------------|--------|--------------|--------------------|------|----------------|--------------|-------------------------------|--------------------|--------------|-------------------------|---------|
| LM10011SD/NOPB   | ACTIVE | WSON         | DSC                | 10   | 1000           | RoHS & Green | SN                            | Level-1-260C-UNLIM | -40 to 125   | L271B                   | Samples |
| LM10011SDX/NOPB  | ACTIVE | WSON         | DSC                | 10   | 4500           | RoHS & Green | SN                            | Level-1-260C-UNLIM | -40 to 125   | L271B                   | Samples |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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10-Dec-2020

## **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width     |
|----|---|
| В0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

| Device          | Package<br>Type | Package<br>Drawing |    | SPQ  | Reel<br>Diameter<br>(mm) | Reel<br>Width<br>W1 (mm) | A0<br>(mm) | B0<br>(mm) | K0<br>(mm) | P1<br>(mm) | W<br>(mm) | Pin1<br>Quadrant |
|-----------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| LM10011SD/NOPB  | WSON            | DSC                | 10 | 1000 | 178.0                    | 12.4                     | 3.3        | 3.3        | 1.0        | 8.0        | 12.0      | Q1               |
| LM10011SDX/NOPB | WSON            | DSC                | 10 | 4500 | 330.0                    | 12.4                     | 3.3        | 3.3        | 1.0        | 8.0        | 12.0      | Q1               |

**PACKAGE MATERIALS INFORMATION** 

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### \*All dimensions are nominal

| Device          | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LM10011SD/NOPB  | WSON         | DSC             | 10   | 1000 | 210.0       | 185.0      | 35.0        |
| LM10011SDX/NOPB | WSON         | DSC             | 10   | 4500 | 367.0       | 367.0      | 35.0        |



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